**DUAL, 1-TO-1** 

## DIFFERENTIAL-TO-LVCMOS TRANSLATOR BUFFER

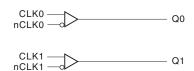
### GENERAL DESCRIPTION

The ICS83023I is a dual, 1-to-1 Differential-to-LVCMOS Translator/Fanout Buffer. The differential inputs can accept most differential signal types (LVDS, LVHSTL, LVPECL, SSTL, and HCSL) and translate into two single-ended LVCMOS outputs. The small 8-lead SOIC footprint makes this device ideal for use in applications with limited board space.

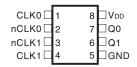
### **Features**

- Two LVCMOS / LVTTL outputs
- Two differential CLKx, nCLKx input pairs
- CLK, nCLK pairs can accept the following differential input levels: LVDS, LVPECL, LVHSTL, SSTL, HCSL
- · Maximum output frequency: 350MHz (typical)
- Output skew: 60ps (maximum)
- Part-to-part skew: 500ps (maximum)
- Additive phase jitter, RMS: 0.14ps (typical)
- Small 8 lead SOIC package saves board space
- 3.3V operating supply
- -40°C to 85°C ambient operating temperature
- Available in both standard and lead-free RoHS-compliant packages

### **BLOCK DIAGRAM**



### PIN ASSIGNMENT



### ICS83023I 8-Lead SOIC

3.8mm x 4.8mm x 1.47mm package body

M Package

Top View



## Dual, 1-to-1 Differential-to-LVCMOS Translator/Buffer

TABLE 1. PIN DESCRIPTIONS

Number	Name	Ту	ре	Description	
1	CLK0	Input	Pulldown	Non-inverting differential clock input.	
2	nCLK0	Input	Pullup	Inverting differential clock input.	
3	nCLK1	Input	Pullup	Inverting differential clock input.	
4	CLK1	Input	Pulldown	Non-inverting differential clock input.	
5	GND	Power		Power supply ground.	
6	Q1	Output		Single clock output. LVCMOS / LVTTL interface levels.	
7	Q0	Output		Single clock output. LVCMOS / LVTTL interface levels.	
8	V <sub>DD</sub>	Power		Positive supply pin.	

NOTE: Pullup and Pulldown refer to internal input resistors. See Table 2, Pin Characteristics, for typical values.

TABLE 2. PIN CHARACTERISTICS

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
C <sub>IN</sub>	Input Capacitance			4		pF
C <sub>PD</sub>	Power Dissipation Capacitance (per output)	V <sub>DD</sub> = 3.6V		23		pF
R <sub>PULLUP</sub>	Input Pullup Resistor			51		kΩ
R <sub>PULLDOWN</sub>	Input Pulldown Resistor			51		kΩ
R <sub>OUT</sub>	Output Impedance			7		Ω



### **ICS830231**

Dual, 1-TO-1

## DIFFERENTIAL-TO-LVCMOS TRANSLATOR / BUFFER

### **ABSOLUTE MAXIMUM RATINGS**

Supply Voltage, V<sub>DD</sub> 4.6V

Inputs,  $V_I$  -0.5 V to  $V_{DD}$  + 0.5 V

Outputs,  $V_{O}$  -0.5V to  $V_{DD}$  + 0.5V

Package Thermal Impedance, θ<sub>IA</sub> 112.7°C/W (0 Ifpm)

Storage Temperature,  $T_{STG}$  -65°C to 150°C

NOTE: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

Table 3A. Power Supply DC Characteristics,  $V_{DD} = 3.3V \pm 0.3V$ ,  $T_A = -40^{\circ}C$  to  $85^{\circ}C$ 

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V <sub>DD</sub>	Positive Supply Voltage		3.0	3.3	3.6	V
I <sub>DD</sub>	Positive Supply Current				20	mA

Table 3B. LVCMOS / LVTTL DC Characteristics,  $V_{DD} = 3.3V \pm 0.3V$ , TA = -40°C to 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V <sub>OH</sub>	Output High Voltage; NOTE 1		2.6			V
V <sub>OL</sub>	Output Low Voltage; NOTE 1				0.5	V

NOTE 1: Outputs terminated with  $50\Omega$  to  $V_{DD}/2$ . See Parameter Measurement Section, 3.3V Output Load Test Circuit.

Table 3C. Differential DC Characteristics,  $V_{DD} = 3.3V \pm 0.3V$ ,  $T_A = -40$ °C to 85°C

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
1	Input High Current	nCLK0, nCLK1	$V_{IN} = V_{DD} = 3.6V$			5	μΑ
I <sub>IH</sub>	I input High Current	CLK0, CLK1	$V_{IN} = V_{DD} = 3.6V$			150	μΑ
	Input Low Current	nCLK0, nCLK1	$V_{IN} = 0V, V_{DD} = 3.6V$	-150			μA
' <sub>IL</sub>		CLK0, CLK1	$V_{IN} = 0V, V_{DD} = 3.6V$	-5			μΑ
V <sub>PP</sub>	Peak-to-Peak Input Voltage			0.15		1.3	V
V <sub>CMR</sub>	Common Mode Inpu NOTE 1, 2	ut Voltage;		GND + 0.5		V <sub>DD</sub> - 0.85	V

NOTE 1: For single-ended applications, the maximum input voltage for CLKx, nCLKx is  $V_{DD}$  + 0.3V.

NOTE 2: Common mode voltage is defined as  $\rm V_{\mbox{\tiny IH}}$ 



Dual, 1-TO-1

## DIFFERENTIAL-TO-LVCMOS TRANSLATOR BUFFER

**Table 4. AC Characteristics,**  $V_{DD} = 3.3V \pm 0.3V$ ,  $TA = -40^{\circ}C$  to  $85^{\circ}C$ 

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
f <sub>MAX</sub>	Maximum Output Frequency			350		MHz
t <sub>PD</sub>	Propagation Delay; NOTE 1		1.8	2.1	2.4	ns
tsk(o)	Output Skew; NOTE 2, 4				60	ps
tsk(pp)	Part-to-Part Skew; NOTE 3, 4				500	ps
<i>t</i> jit	Buffer Additive Phase Jitter, RMS; refer to Additive Phase Jitter Section	100MHz, Integration Range (637kHz-10MHz)		0.14		ps
t <sub>R</sub>	Output Rise Time	0.8V to 2V	100	250	400	ps
t <sub>F</sub>	Output Fall Time	0.8V to 2V	100	250	400	ps
odc	Output Duty Cycle	f ≤ 166MHz	45	50	55	%
	Output Duty Cycle	f > 166MHz	43	50	57	%

All parameters measured at  $f_{\text{MAX}}$  unless noted otherwise. See Parameter Measurement Information.

NOTE 1: Measured from the differential input crossing point to  $V_{\tiny DD}\!/\!2$  of the output.

NOTE 2: Defined as skew between outputs at the same supply voltage and with equal load conditions.

Measured at V<sub>DD</sub>/2. Input clocks are phase aligned.

NOTE 3: Defined as skew between outputs on different devices operating at the same supply voltages and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at  $V_{pp}/2$ .

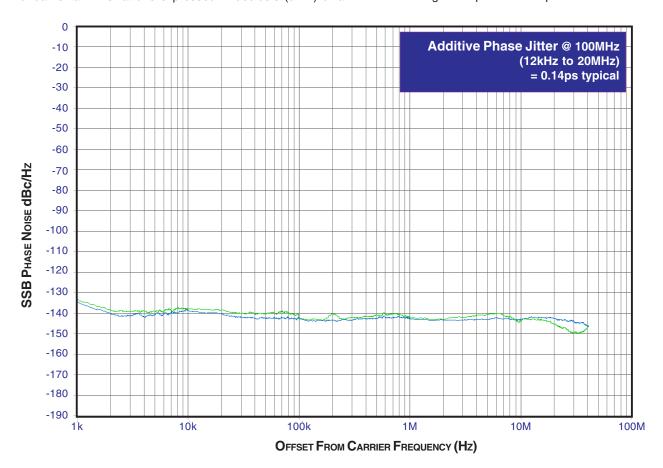
NOTE 4: This parameter is defined in accordance with JEDEC Standard 65.

## ICS83023I Dual, 1-to-1 DIFFERENTIAL-TO-LVCMOS TRANSLATOR/BUFFER

### **ADDITIVE PHASE JITTER**

The spectral purity in a band at a specific offset from the fundamental compared to the power of the fundamental is called the *dBc Phase Noise*. This value is normally expressed using a Phase noise plot and is most often the specified plot in many applications. Phase noise is defined as the ratio of the noise power present in a 1Hz band at a specified offset from the fundamental frequency to the power value of the fundamental. This ratio is expressed in decibels (dBm) or a

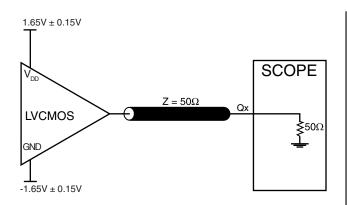
ratio of the power in the 1Hz band to the power in the fundamental. When the required offset is specified, the phase noise is called a *dBc* value, which simply means dBm at a specified offset from the fundamental. By investigating jitter in the frequency domain, we get a better understanding of its effects on the desired application over the entire time record of the signal. It is mathematically possible to calculate an expected bit error rate given a phase noise plot.

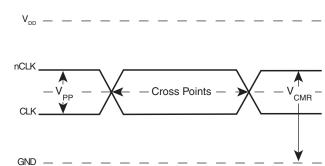


As with most timing specifications, phase noise measurements have issues. The primary issue relates to the limitations of the equipment. Often the noise floor of the equipment is higher than the noise floor of the device. This is illustrated above. The device meets the noise floor of what is shown, but can actually be lower. The phase noise is dependant on the input source and measurement equipment.

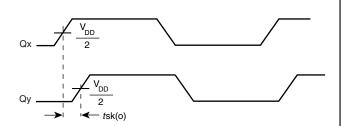


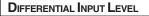
## PARAMETER MEASUREMENT INFORMATION

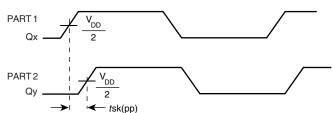




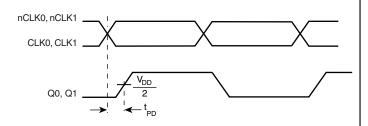
### 3.3V OUTPUT LOAD ACTEST CIRCUIT



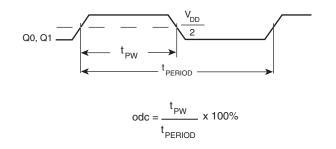




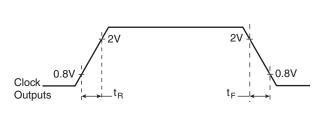
### **OUTPUT SKEW**



### PART-TO-PART SKEW



### **PROPAGATION DELAY**



### OUTPUT DUTY CYCLE/PULSE WIDTH/PERIOD

### OUTPUT RISE/FALL TIME

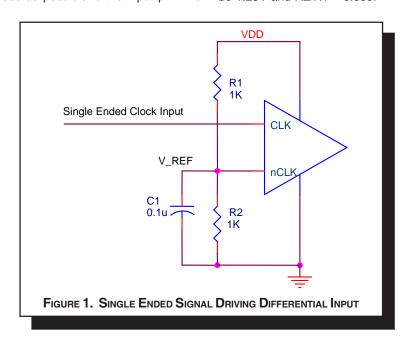
## ICS83023I DUAL, 1-TO-1 DIFFERENTIAL-TO-LVCMOS TRANSLATOR/BUFFER

### **APPLICATION INFORMATION**

### WIRING THE DIFFERENTIAL INPUT TO ACCEPT SINGLE ENDED LEVELS

Figure 1 shows how the differential input can be wired to accept single ended levels. The reference voltage  $V_REF = V_{DD}/2$  is generated by the bias resistors R1, R2 and C1. This bias circuit should be located as close as possible to the input pin. The

ratio of R1 and R2 might need to be adjusted to position the V\_REF in the center of the input voltage swing. For example, if the input clock swing is only 2.5V and V\_DD = 3.3V, V\_REF should be 1.25V and R2/R1 = 0.609.



### RECOMMENDATIONS FOR UNUSED INPUT AND OUTPUT PINS

INPUTS: OUTPUTS:

### CLK/nCLK INPUT:

For applications not requiring the use of the differential input, both CLK and nCLK can be left floating. Though not required, but for additional protection, a  $1k\Omega$  resistor can be tied from CLK to ground.

### LVCMOS OUTPUT:

All unused LVCMOS output can be left floating. We recommend that there is no trace attached.



### DIFFERENTIAL CLOCK INPUT INTERFACE

The CLK /nCLK accepts LVDS, LVPECL, LVHSTL, SSTL, HCSL and other differential signals. Both  $V_{\text{SWING}}$  and  $V_{\text{OH}}$  must meet the  $V_{\text{PP}}$  and  $V_{\text{CMR}}$  input requirements. Figures 2A to 2E show interface examples for the CLK/nCLK input driven by the most common driver types. The input interfaces suggested

here are examples only. Please consult with the vendor of the driver component to confirm the driver termination requirements. For example in *Figure 2A*, the input termination applies for LVHSTL drivers. If you are using an LVHSTL driver from another vendor, use their termination recommendation.

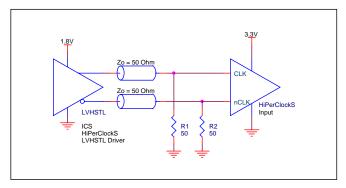


FIGURE 2A. CLK/nCLK INPUT DRIVEN BY LVHSTL DRIVER

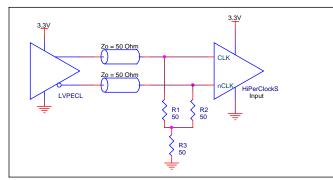


FIGURE 2B. CLK/nCLK INPUT DRIVEN BY 3.3V LVPECL DRIVER

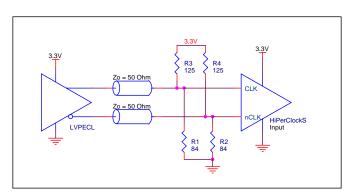


FIGURE 2C. CLK/nCLK INPUT DRIVEN BY 3.3V LVPECL DRIVER

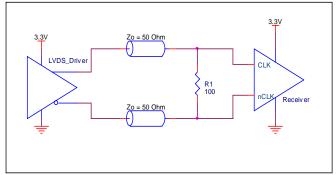


FIGURE 2D. CLK/nCLK INPUT DRIVEN BY 3.3V LVDS DRIVER

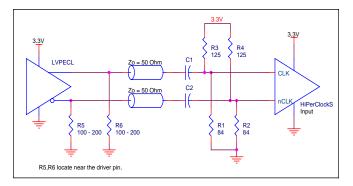


FIGURE 2E. CLK/NCLK INPUT DRIVEN BY
3.3V LVPECL DRIVER WITH AC COUPLE

# ICS83023I DUAL, 1-TO-1 DIFFERENTIAL-TO-LVCMOS TRANSLATOR/BUFFER

### RELIABILITY INFORMATION

### Table 5. $\theta_{\rm JA} {\rm vs.}$ Air Flow Table for 8 Lead SOIC

### $\theta_{AA}$ by Velocity (Linear Feet per Minute)

0200500Single-Layer PCB, JEDEC Standard Test Boards153.3°C/W128.5°C/W115.5°C/WMulti-Layer PCB, JEDEC Standard Test Boards112.7°C/W103.3°C/W97.1°C/W

NOTE: Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.

#### TRANSISTOR COUNT

The transistor count for ICS83023I is: 416



### PACKAGE OUTLINE - SUFFIX M FOR 8 LEAD SOIC

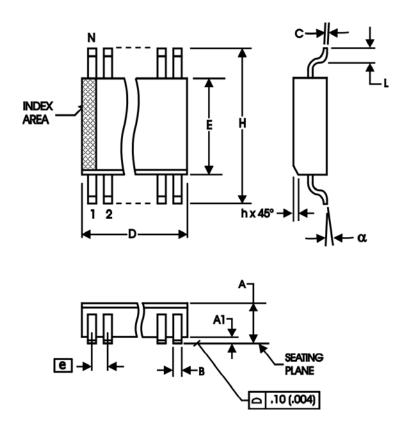


TABLE 6. PACKAGE DIMENSIONS

SYMBOL	Millimeters			
STWIBOL	MINIMUN	MAXIMUM		
N	8	3		
A	1.35	1.75		
A1	0.10	0.25		
В	0.33	0.51		
С	0.19	0.25		
D	4.80	5.00		
E	3.80	4.00		
е	1.27 [	BASIC		
Н	5.80	6.20		
h	0.25	0.50		
L	0.40	1.27		
α	0°	8°		

Reference Document: JEDEC Publication 95, MS-012



# ICS83023I Dual, 1-to-1 DIFFERENTIAL-TO-LVCMOS TRANSLATOR/BUFFER

#### TABLE 7. ORDERING INFORMATION

Part/Order Number	Marking	Package	Shipping Packaging	Temperature
83023AMI	83021AMI	8 lead SOIC	tube	-40°C to 85°C
83023AMIT	83021AMI	8 lead SOIC	2500 tape & reel	-40°C to 85°C
83023AMILF	83023AIL	8 lead "Lead-Free" SOIC	tube	-40°C to 85°C
83023AMILFT	83023AIL	8 lead "Lead-Free" SOIC	2500 tape & reel	-40°C to 85°C

NOTE: Parts that are ordered with an "LF" suffix to the part number are the Pb-Free configuration and are RoHS compliant.

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## Dual, 1-to-1 Differential-to-LVCMOS Translator/Buffer

	REVISION HISTORY SHEET						
Rev	Table	Page	Description of Change	Date			
А	7	11	Ordering Information Table - corrected Part/Order Number for Tape & Reel to read ICS83023AMIT from ICS83023AMI.	09/09/02			
В	T2 T4	1 2 4 5 7 8 11	Features Section - added Additive Phase Jitter and Lead-Free bullets. Pin Characteristics Table - changed C <sub>IN</sub> from 4pF max. to 4pF typical. AC Characteristics Table - added Additive Phase Jitter row. Added Additive Phase Jitter Plot. Added Recommendations for Unused Input and Output Pins. Added Differential Clock Input Interface. Ordering Information Table - added Lead-Free Part Number and Note. Update datasheet format.	12/12/05			
В	T7	11	Ordering information Table - added Lead-Free marking.	1/18/08			
В	Т7	11 13	Updated datasheet's header/footer with IDT from ICS. Removed ICS prefix from Part/Order Number column. Added Contact Page.	7/29/10			



## ICS83023I DUAL, 1-TO-1 DIFFERENTIAL-TO-LVCMOS TRANSLATOR/BUFFER

## We've Got Your Timing Solution.



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